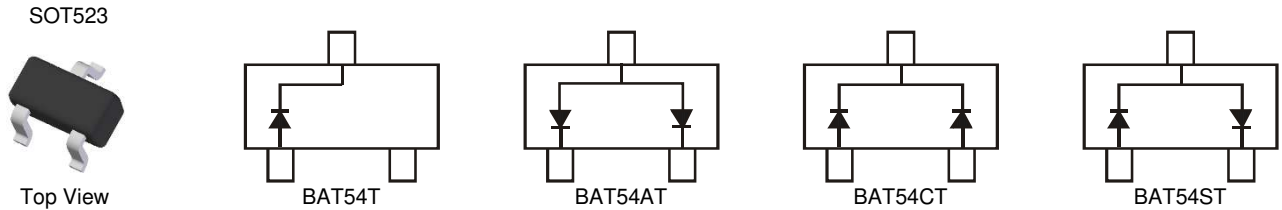


Features

- Ultra-Small Surface-Mount Package
- Low-Forward Voltage Drop
- Fast Switching
- PN Junction Guard Ring for Transient and ESD Protection
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **An automotive-compliant part is available under separate datasheet ([BAT54TQ/STQ](#))**

Mechanical Data

- Package: SOT523
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (E3)
- Lead-Free Plating
- Polarity: See Diagrams Below
- Weight: 0.002 grams (Approximate)

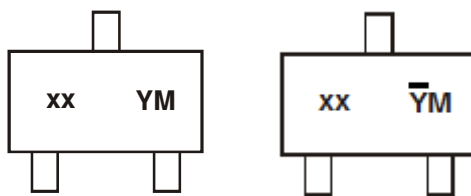


Ordering Information (Note 4)

Part Number	Package	Packing	
		Qty.	Carrier
BAT54T-7-F	SOT523	3,000	Tape & Reel
BAT54AT-7-F	SOT523	3,000	Tape & Reel
BAT54CT-7-F	SOT523	3,000	Tape & Reel
BAT54ST-7-F	SOT523	3,000	Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



xx = Product Type Marking Code
 L1 = BAT54T
 L2 = BAT54AT
 L3 = BAT54CT
 L4 = BAT54ST
 YM or YM = Date Code Marking
 Y or Y = Year (ex: K = 2023)
 M = Month (ex: 5 = May)

Date Code Key

Year	2003	-	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032
Code	P	-	K	L	M	N	P	R	S	T	U	V

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	30	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
Forward Continuous Current (Note 5)	I _{FM}	200	mA
Repetitive Peak Forward Current	I _{FRM}	300	mA
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine Wave Superimposed on Rated Load	I _{FSM}	600	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	220	mW
Typical Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	570	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V _{(BR)R}	30	—	—	V	I _R = 100μA
Forward Voltage	V _F	—	—	240	mV	I _F = 0.1mA
		—	—	320		I _F = 1mA
		—	—	400		I _F = 10mA
		—	—	500		I _F = 30mA
		—	—	1,000		I _F = 100mA
Reverse Leakage Current (Note 6)	I _R	—	—	2.0	μA	V _R = 25V
Total Capacitance	C _T	—	—	10	pF	V _R = 10V, f = 1.0MHz
Reverse Recovery Time	t _{RR}	—	—	5.0	ns	I _F = I _R = 10mA I _{RR} = 0.1 x I _R , R _L = 100Ω

- Notes:
- Device mounted on FR-4 substrate PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com/package-outlines.html>.
 - Short duration pulse test used to minimize self-heating effect.

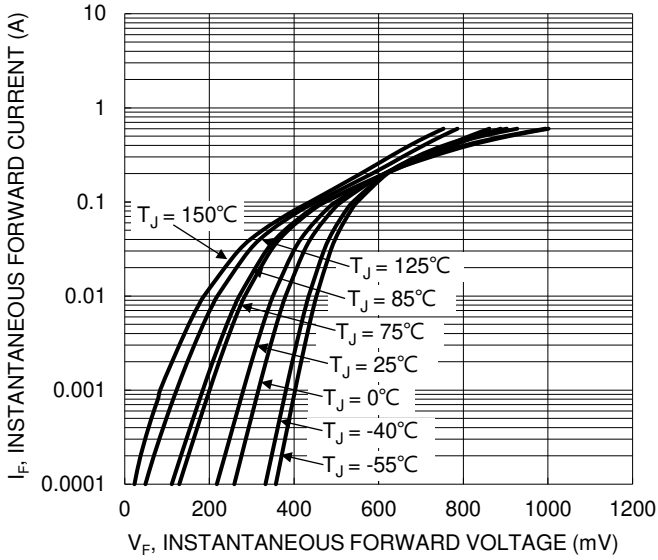


Figure 1. Typical Forward Characteristics

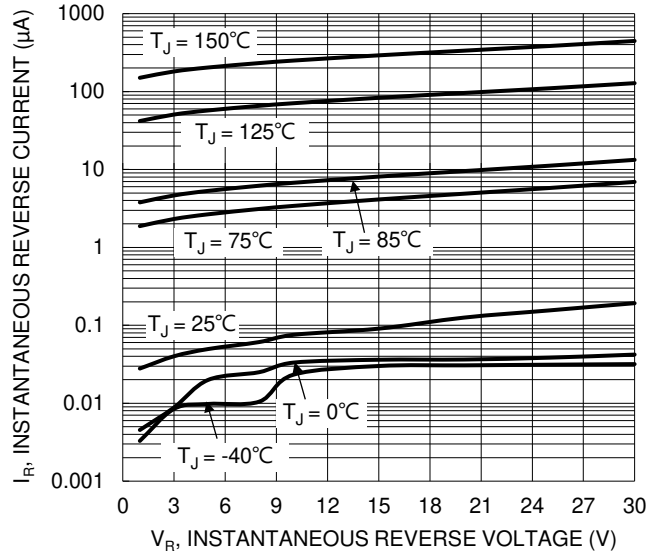


Figure 2. Typical Reverse Characteristics

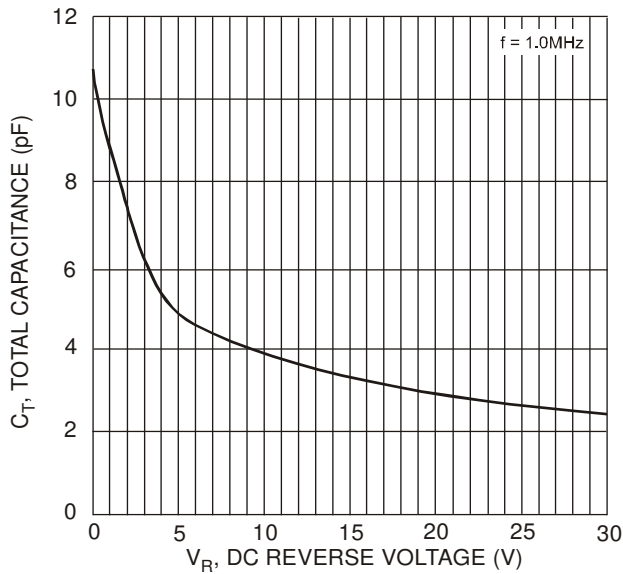


Figure 3. Total Capacitance vs. Reverse Voltage

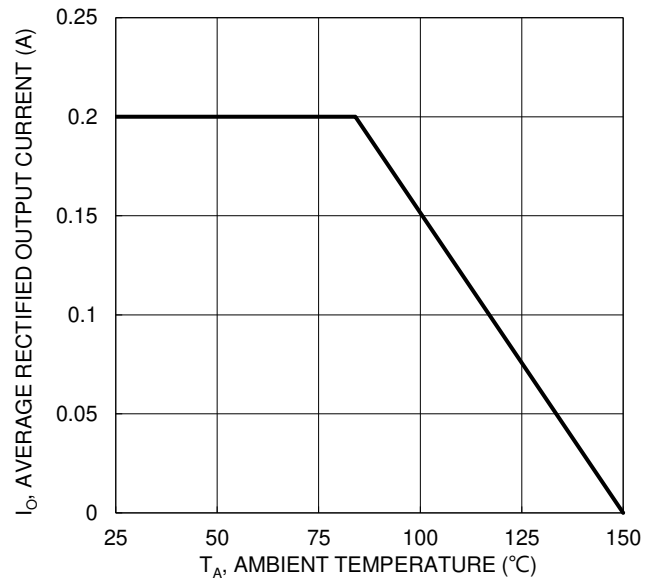
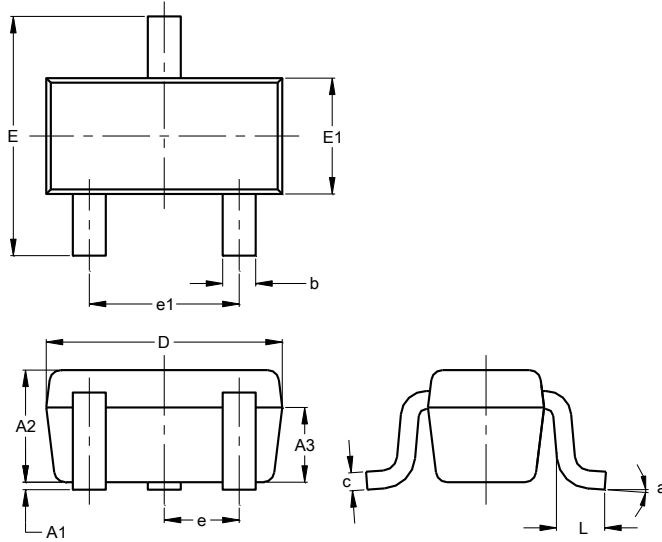


Figure 4. DC Forward Current Derating

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT523

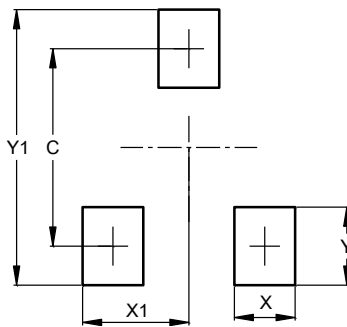


SOT523			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.60	0.80	0.75
A3	0.45	0.65	0.50
b	0.15	0.30	0.22
c	0.10	0.20	0.12
D	1.50	1.70	1.60
E	1.45	1.75	1.60
E1	0.75	0.85	0.80
e	0.50 BSC		
e1	0.90	1.10	1.00
L	0.20	0.40	0.33
a	0°	--	8°
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT523



Dimensions	Value (in mm)
C	1.29
X	0.40
X1	0.70
Y	0.51
Y1	1.80

- Notes:
- The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These dimensions may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.
 - For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

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